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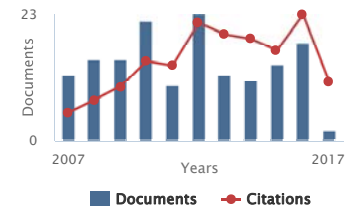
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Learning based compact thermal modeling for energy-efficient smart building management	Zhao, H., Quach, D., Wang, S., (...), Li, X., Tan, S.X.-D.	2016	2015 IEEE/ACM International Conference on Computer-Aided Design, ICCAD 2015	1
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